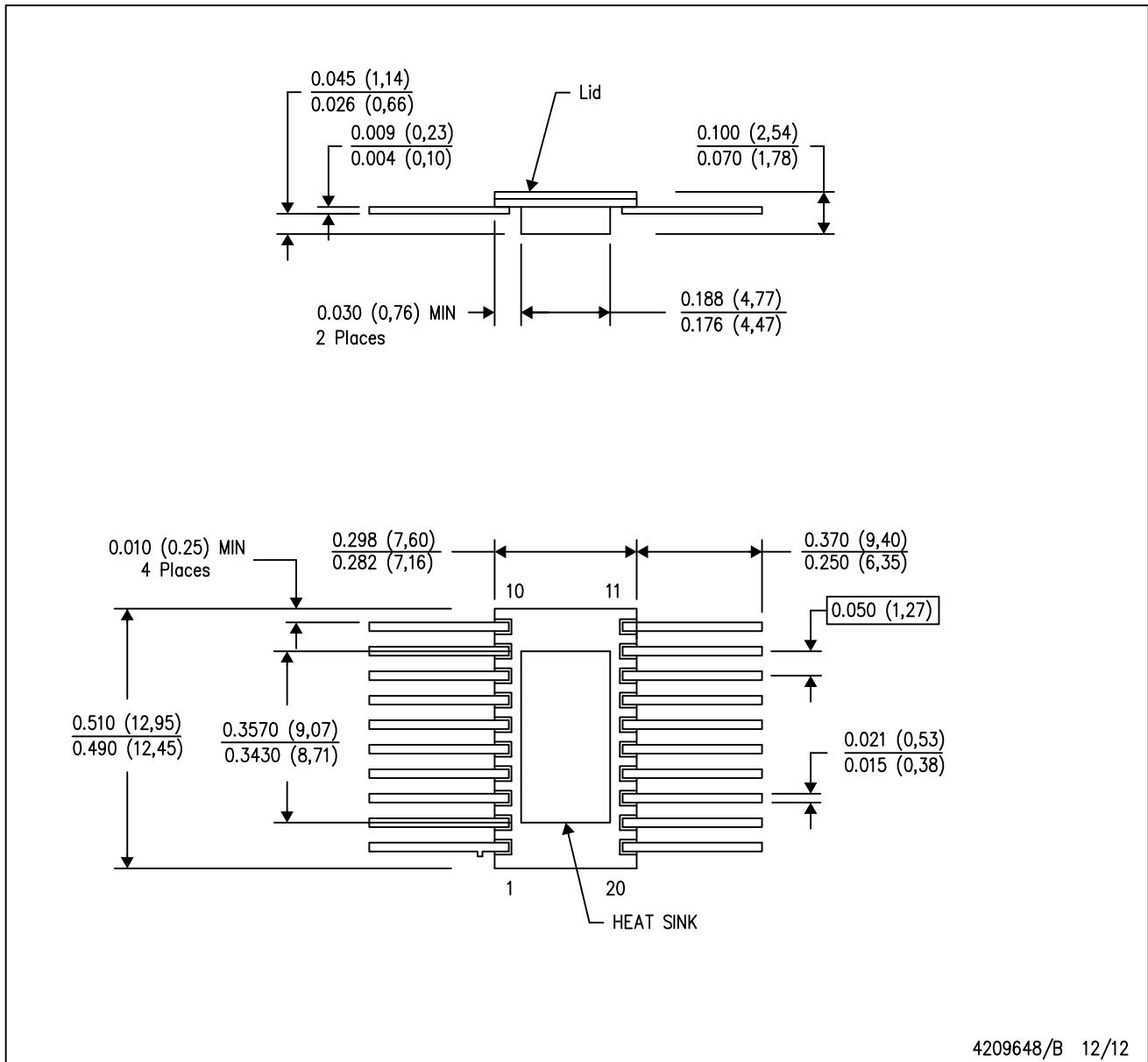


HKH (R-CDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - The terminals will be gold plated.
 - Falls within MIL STD 1835 CDFP3-F20.

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